

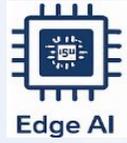
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Product Manager, Automotive & Industrial SOI

# ENGINEERED SUBSTRATES FOR SECURE, RESILIENT EDGE AI, IOT & AUTOMOTIVE SOCS

MPSoC, Megeve | 16.06.25

# EMERGING SOC DEMANDS ACROSS EDGE AI, IOT & AUTOMOTIVE

COMPUTE MOVES CLOSER TO THE EDGE: SECURITY, RELIABILITY, POWER EFFICIENCY

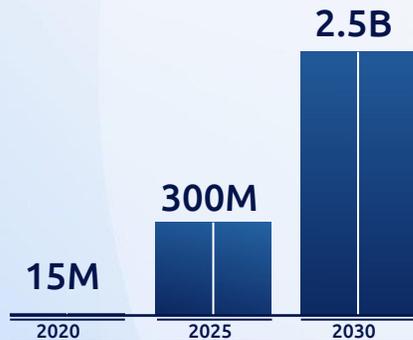


Edge AI



IoT

EDGE AI CHIPSET MARKET (UNITS)



Source: ABI research 2021



LOW POWER CONSUMPTION - ALWAYS ON



PERFORMANCE ON DEMAND



TAMPER PROOF - SECURE PROCESSING

Trust  
Secure Processing

Latency/  
Local AI



Resilience  
Harsh Environment Operation

Efficiency  
Local Power / High Integration



SEMICONDUCTOR CONTENT PER CAR (\$)



Source: UBS, Soitec estimates



HIGH ROBUSTNESS & FUSA



HIGH INTEGRATION



HIGH EFFICIENCY & LIFETIME

# ENGINEERED SUBSTRATES: FOUNDATION FOR SECURE, RESILIENT SOCS

Security, Efficiency, And Resilience—Engineered From The Substrate Up

The physical layer plays an important role in



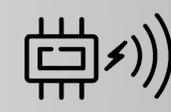
Soft error susceptibility



Leakage and variability



Thermal instability



Crosstalk/interference

*Start at the bottom: Trust begins in silicon*

## ADVANTAGE FD-SOI

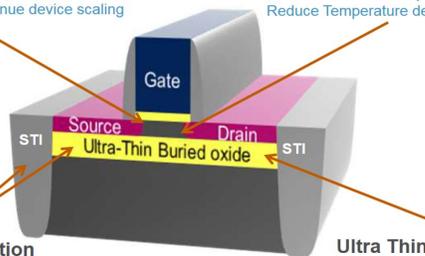
*Thin, undoped fully depleted channel with simple, planar structure giving good electrostatic control and low parasitic*

### Ultra-Thin BODY

Excellent Electrostatic Control of the channel  
Low SCE, DIBL → Low  $V_t$  @ High  $V_D$   
Gate length shrink → continue device scaling

### Undoped Channel & no Pocket

Less  $V_t$  variability & SRAM  $V_{min}$  improved  
Lower Power Consumption  
Reduce Temperature dependency & no RDF



### Total Dielectric Isolation

Lower SD capacitances & Lower SD Leakage  
Less Sensitive to Temperature  
Higher power efficiency

### Ultra Thin BOX

Body Biasing (BB) → FBB & RBB  
Speed boost due to BB  
GP Implantation →  $V_t$  adjustment

Improved SER

Body bias: performance on demand

Improved mismatch

Low leakage/Low power

Latch-up free

Low noise

Soitec in numbers

IN OUR SOIL GROWS AN AMAZING FUTURE



1992

Soitec is founded

530+

Patents filed worldwide in FY25

~4,300

Active patents

11%

of revenue dedicated to gross R&D

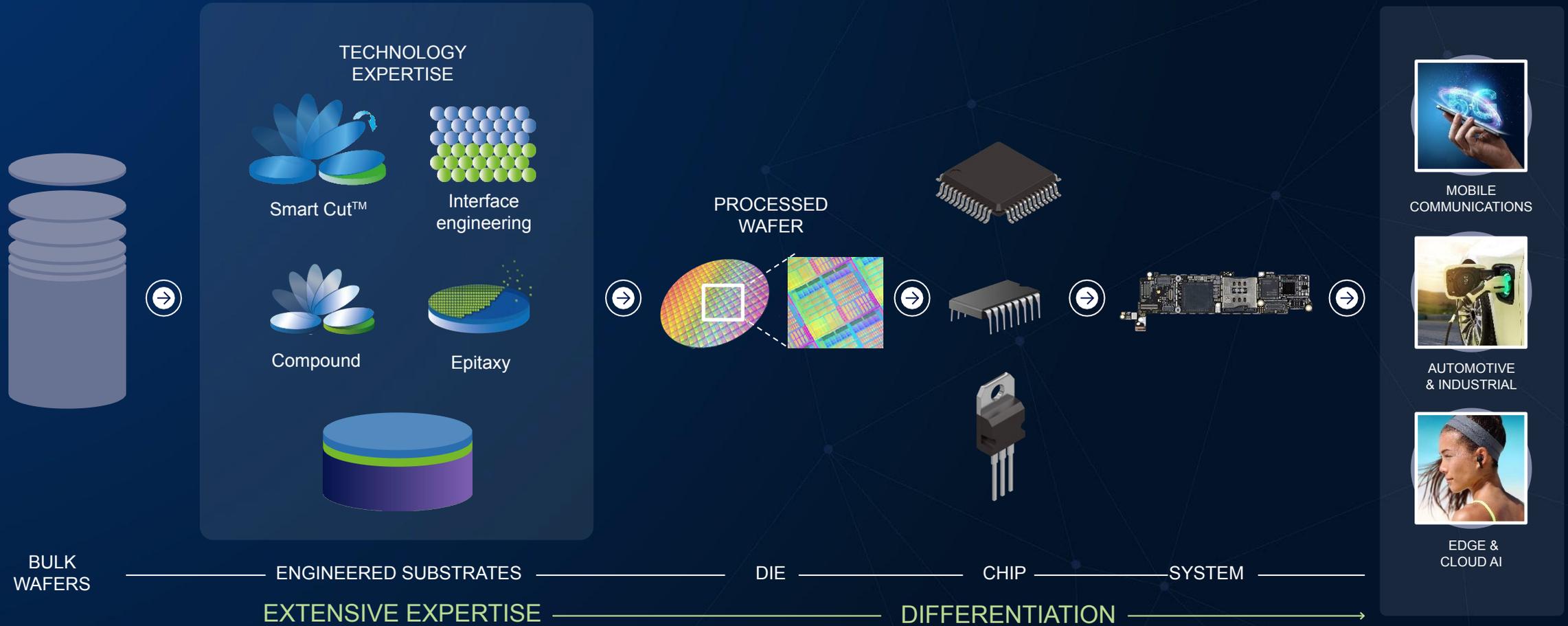
>2300

Employees (35% women)  
industry average 20-25%

891M€

Revenue (Fiscal year 2025)

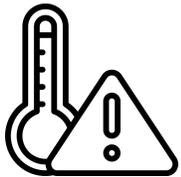
# ENGINEERED SUBSTRATES ARE A CRITICAL COMPONENT OF THE SEMICONDUCTOR INDUSTRY



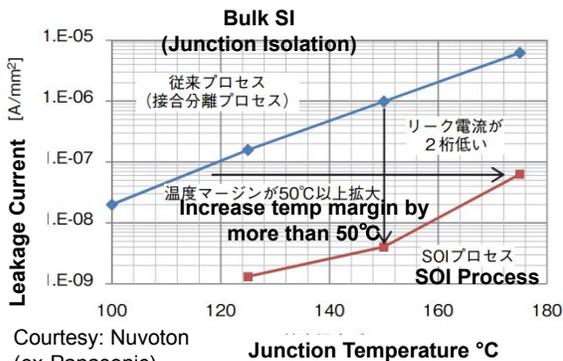
# RESILIENCE UNDER STRESS: SUBSTRATE-ENABLED RELIABILITY

ENABLING RESILIENT SOCS FOR AUTOMOTIVE AND INDUSTRIAL

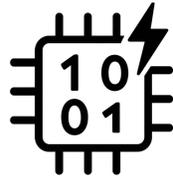
## High temperature operation



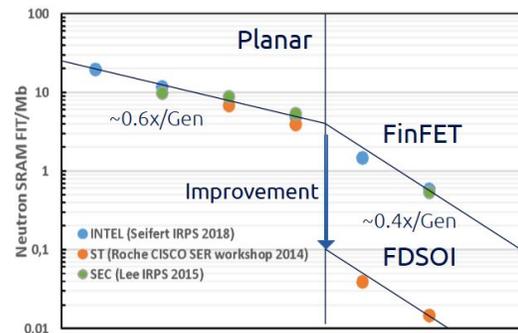
Meeting AEC-Q100C Grade 0 (150-175°C)  
Lower leakage currents



## Radiation exposure



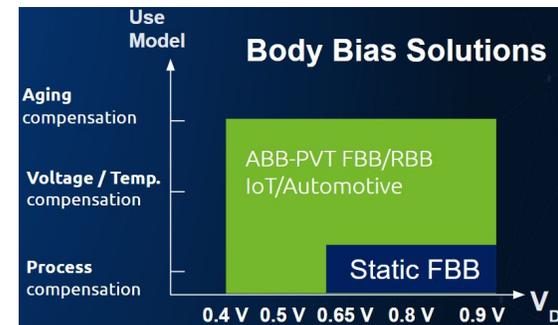
SEU, SER in automotive, avionics, industrial  
BOx reduces charge diffusion  
No latch up



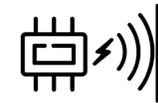
## Aging and variability



Body bias to dynamically compensate aging and PVT variations



## Power/voltage noise sensitivity



Better isolation, reduced substrate coupling

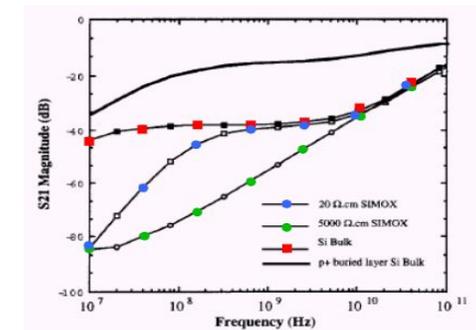
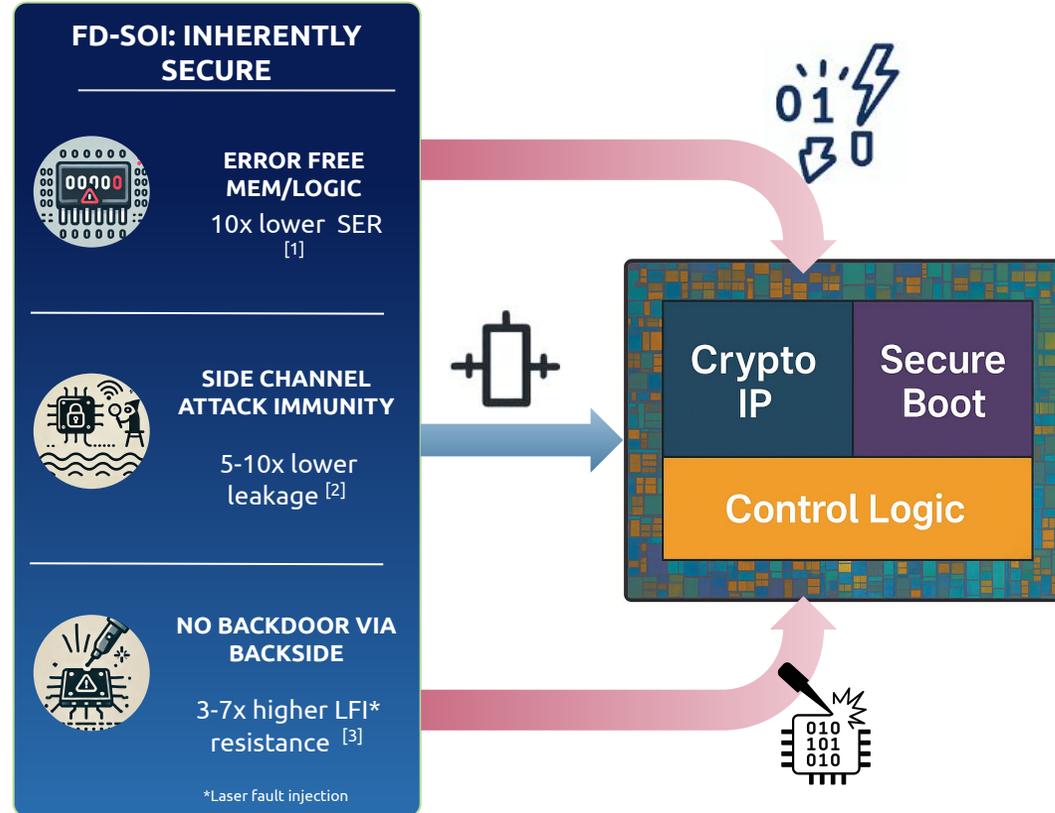


Fig. 2 : Numerical device simulation of crosstalk figures as a function of frequency for the basic test structure on different substrates : bulk with and without buried layer and SOI for 2 different substrate resistivities. The distance between devices is 50 μm.

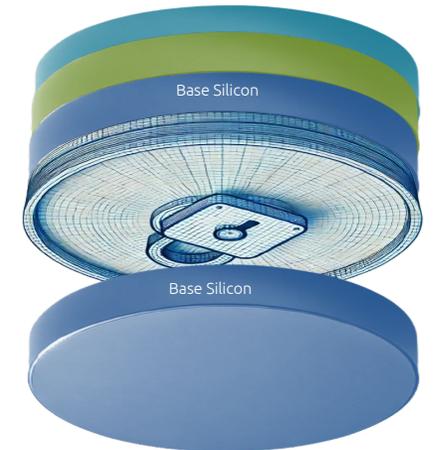


# SECURING SOCS FROM THE SUBSTRATE UP

Security isn't just an IP problem. It starts with the silicon foundation



## A GLIMPSE INTO THE FUTURE: CYBER-SUBSTRATE



A secure layer within the base Silicon

[1] Nguyen, Bich-Yen, et al. "A path to energy efficiency and reliability for ICs: Fully depleted silicon-on-insulator (FD-SOI) devices offer many advantages." IEEE Solid-State Circuits Magazine 10.4 (2018): 24-33.

[2] Planes, Nicolas, et al. "28nm FDSOI technology platform for high-speed low-voltage digital applications." 2012 Symposium on VLSI technology (VLSIT). IEEE, 2012.

[3] Dutertre, Jean-Max, et al. "Sensitivity to laser fault injection: Cmos fd-soi vs. cmos bulk." IEEE Transactions on Device and Materials Reliability 19.1 (2018): 6-15.

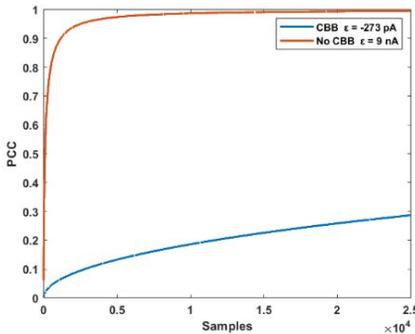
# ENABLING SECURE IP IN FD-SOI WITH BACK BIAS (BB)

## FROM CRYPTO RESILIENCE TO TRNGs



### Back bias as a means to mask the leakage in secure IP<sup>[1]</sup>

Current Balancing Body Bias – using back bias to automatically balance the leakage currents.



### COSO: COSO TRNG using FDSOI<sup>[2]</sup>

BB as a very simple and efficient technique for the ring oscillator frequency calibration needed for the coherent sampling method.

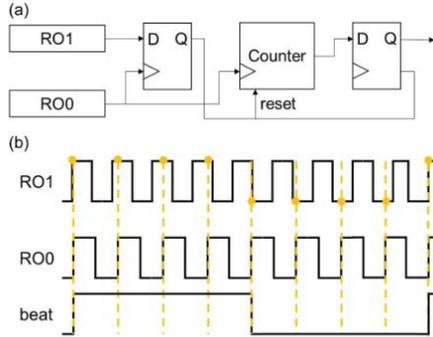
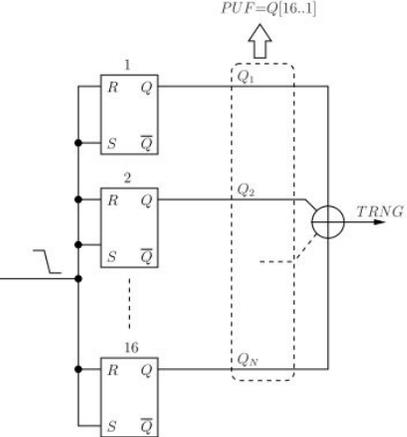


Fig. 2. Architecture of the COSO-TRNG (a) and schematic representations of the signals (b)

### PUF-TRNG circuit based on as set of SR latches<sup>[3]</sup>

An optimal state is obtained for both TRNG and PUF by controlling the latches by the BB of the FD-SOI technology.



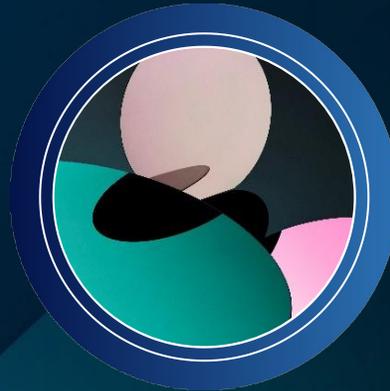
[1] Palma Carmona, Kenneth. "Exploration of FDSOI back-biasing techniques to hinder cryptographic attacks based on leakage current." (2023).  
 [2] Benea, Licinius, et al. "COSO: True Random Number Generator Based on Coherent Sampling using the FD-SOI technology." *WIPIEC Journal-Works in Progress in Embedded Computing Journal* 10.2 (2024).  
 [3] Danger, Jean-Luc, et al. "Analysis of mixed PUF-TRNG circuit based on SR-latches in FD-SOI technology." *2018 21st Euromicro Conference on Digital System Design (DSD)*. IEEE, 2018.



# Advancing Secure Frontier



SECURITY, RELIABILITY, POWER  
EFFICIENCY are increasingly  
demanded by the connected  
INTELLIGENT world



Engineered substrates build  
resilience and security bottom up  
in AUTOMOTIVE to EDGE AI



FDSOI: Inherently resilient  
and secure with BB as an  
extra leverage in secure IP



# THANK YOU

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